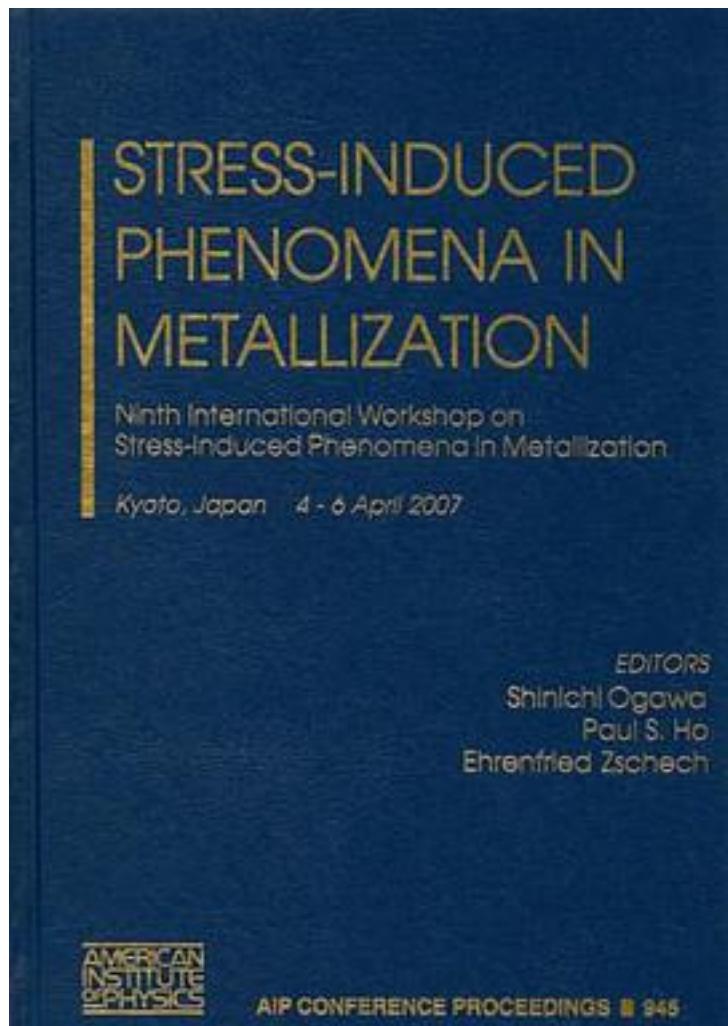


# Stress-induced Phenomena in Metallization



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The conference was on reliability related science in ULSI interconnect. Its main

purpose was to discuss the stress induced phenomena in the LSI interconnect among academic researchers and industry engineers to establish academic science and to improve the reliability of ULSI chips. All papers were peer reviewed.

作者介绍:

目录:

[Stress-induced Phenomena in Metallization\\_下载链接1](#)

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